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# GaN MMIC PAs for MMW Applicaitons

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# Motivation for High Frequency Power sources 60 GHz – 110 GHz Frequency Spectrum

## High Data Rate Wireless Links (10 Gbits/s)

Commercial Bands (E-band radio)

71 GHz – 76 GHz, 81 GHz – 86 GHz, 92 GHz – 95 GHz

Inter-Satellite

59.3 GHz – 64 GHz



## Active Millimeter-Wave Imaging

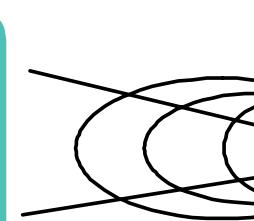
94 GHz SAR, Phase Array Radar

(Space based W-band radar for earth studies.)

## RF Sources for THz Multiplier Diodes

Fundamental Power for THz Space Array

Spectroscopy

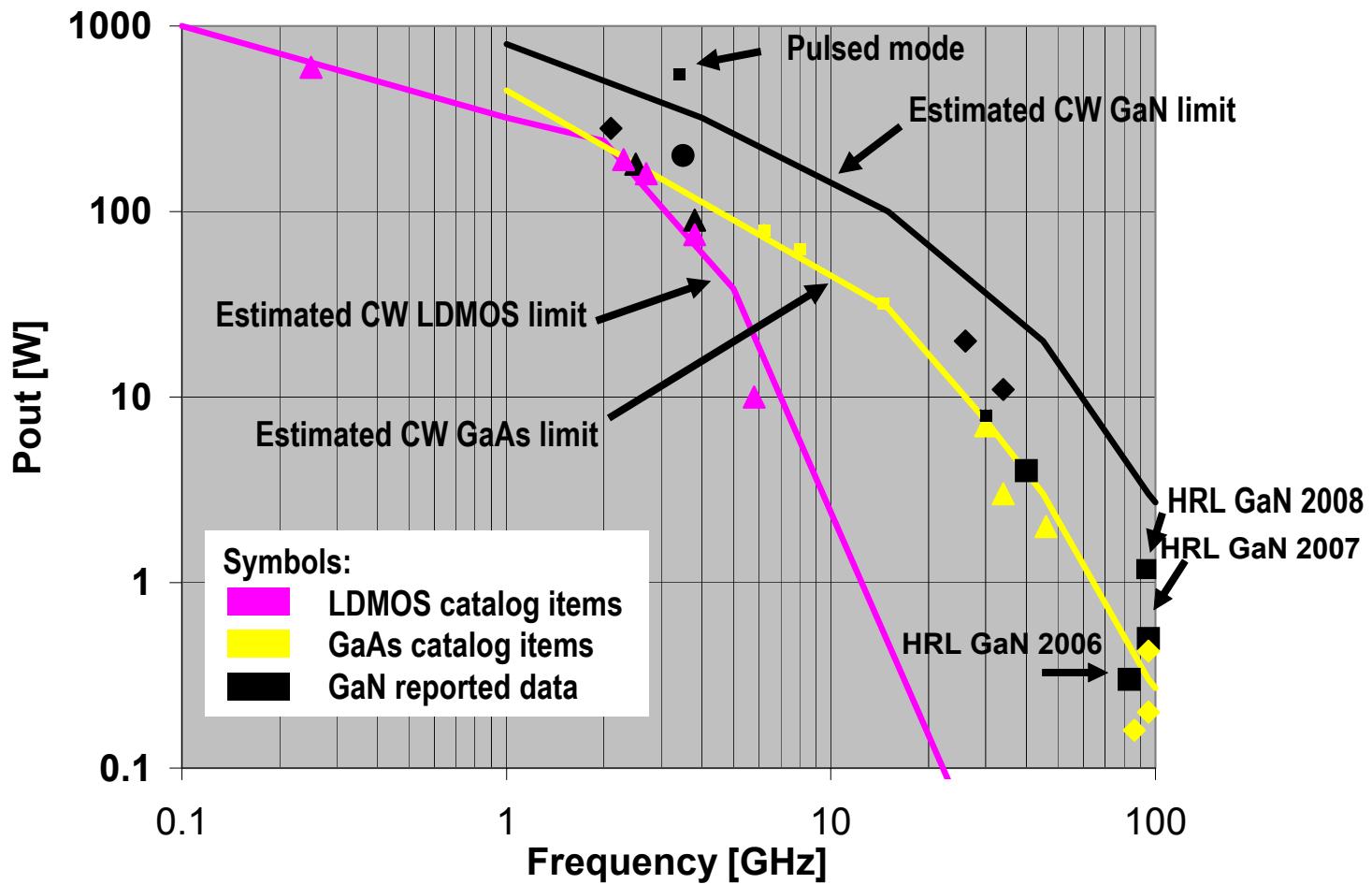


**Power Required  $\approx$  Watts**

**Available Sources  $< 200$  mW**

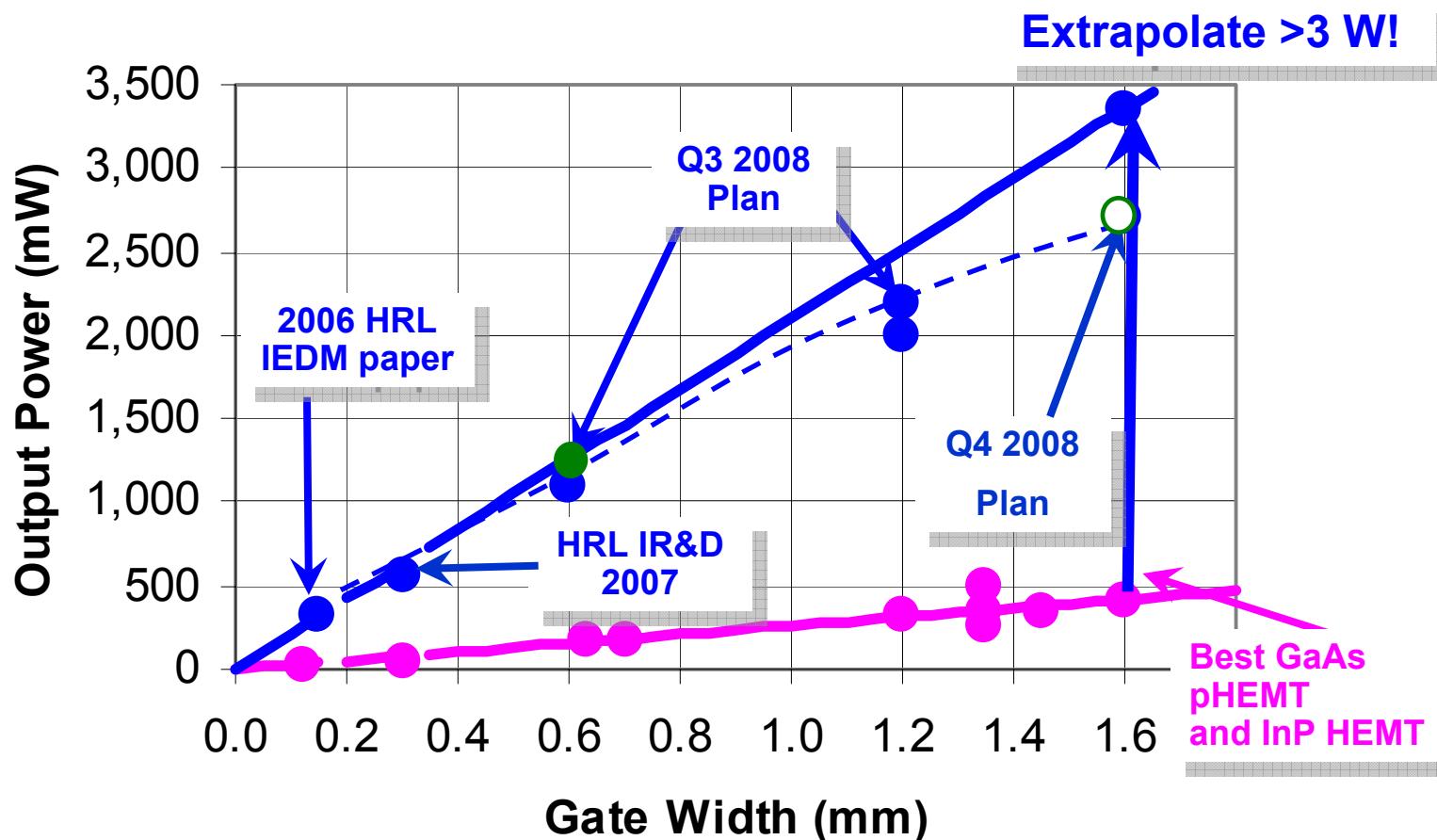
**GaN MMIC  $\approx 3$  W at 95 GHz**

# Microwave and Millimeter-wave Solid State Sources



Output power per single die.

# HRL W-band GaN Roadmap



Disruptive W-band GaN Power MMICs

8X higher power density than mmW GaAs pHEMT

# Cost trade-off estimate for 3 Watt W-band SSPA

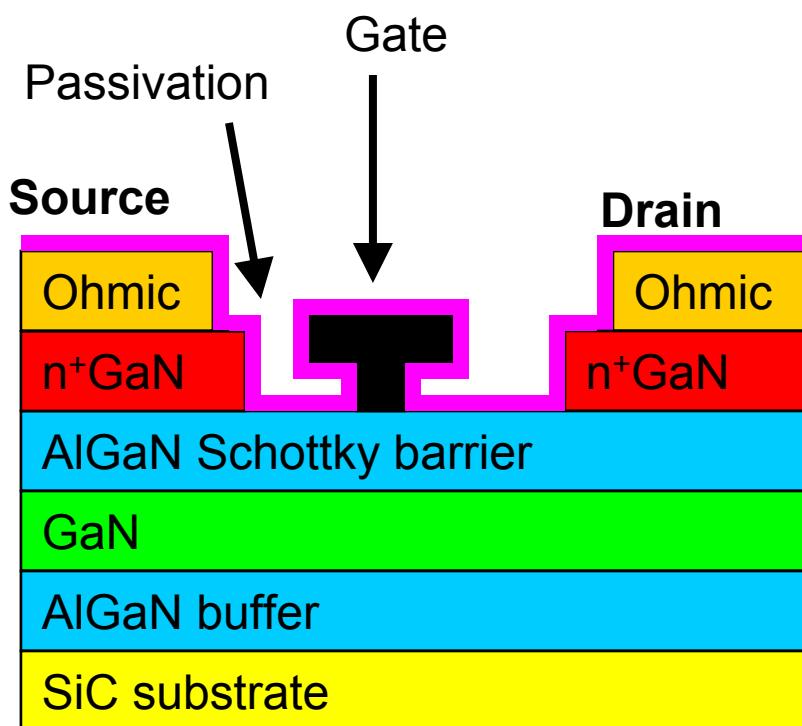
	GaAs pHEMT SSPA	GaN SSPA
<b>8-way waveguide combining</b>	<b>8-way splitter and 8 way combiner required</b>	<b>Power combining not required</b>
<b>Number of WR-10 power modules</b>	<b>8</b>	<b>1</b>
<b>Number of MMIC's per module</b>	<b>3 (Attenuator, Phase Shifter, Power Amplifier)</b>	<b>1 (Power Amplifier only)</b>
<b>Hand-tuning to obtain phase and amplitude match for combining</b>	<b>Combiner arms tuned manually</b>	<b>No tuning</b>



**3 Watt 95 GHz GaN SSPA is Cost Effective**

# W-band GaN MMIC Device

T-gate device  $L_g = 0.12 \mu\text{m}$



N<sup>+</sup> layer facilitates fabrication of ohmic contacts. Double Heterojunction Structure

Low ohmic contact resistance < 0.2 Ω/mm.

Comparable to GaAs pHEMT's and InP HEMT's.

Smooth ohmic metal edges.

Recessed gate

Bi-layer e-beam gate litho

$L_g = 0.12 \mu\text{m}$  for Ka-band

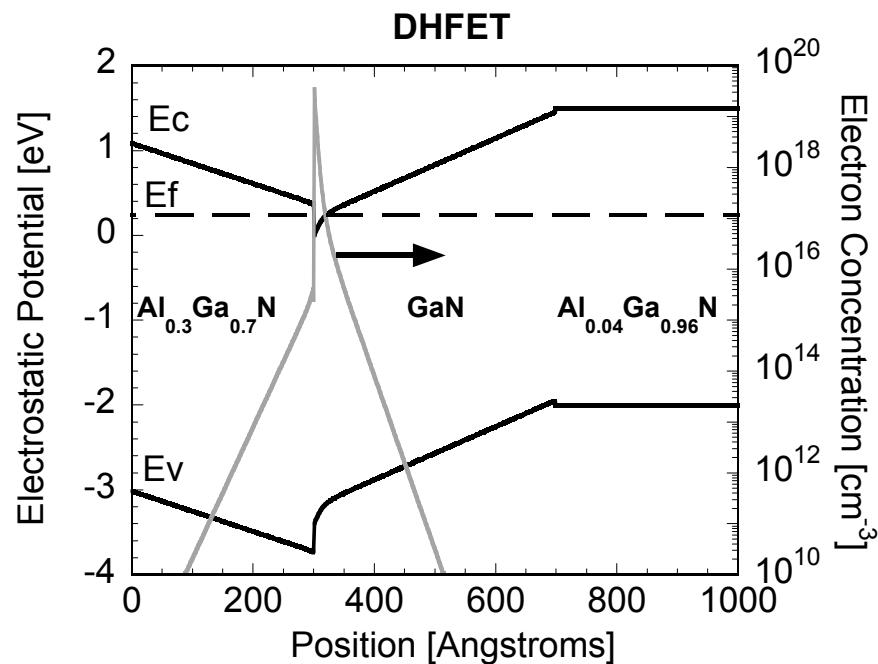
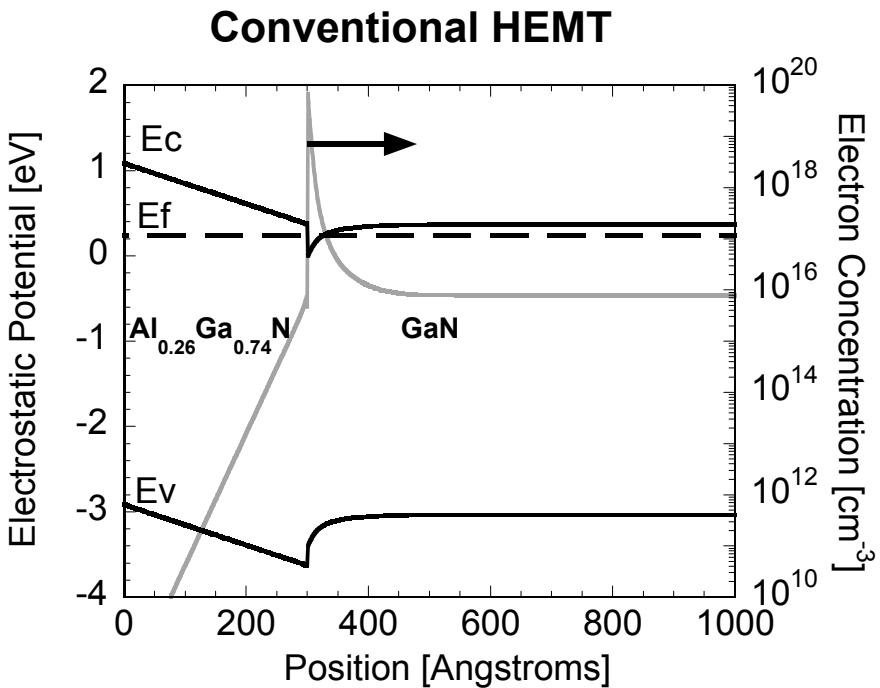
SiN passivation and capacitor dielectric

2 μm Source-Drain separation

TaN 50 Ω/Square resistor

Epi resistors

# Short Channel Effects - Buffer Isolation



**Techniques used to improve backside confinement and buffer isolation**

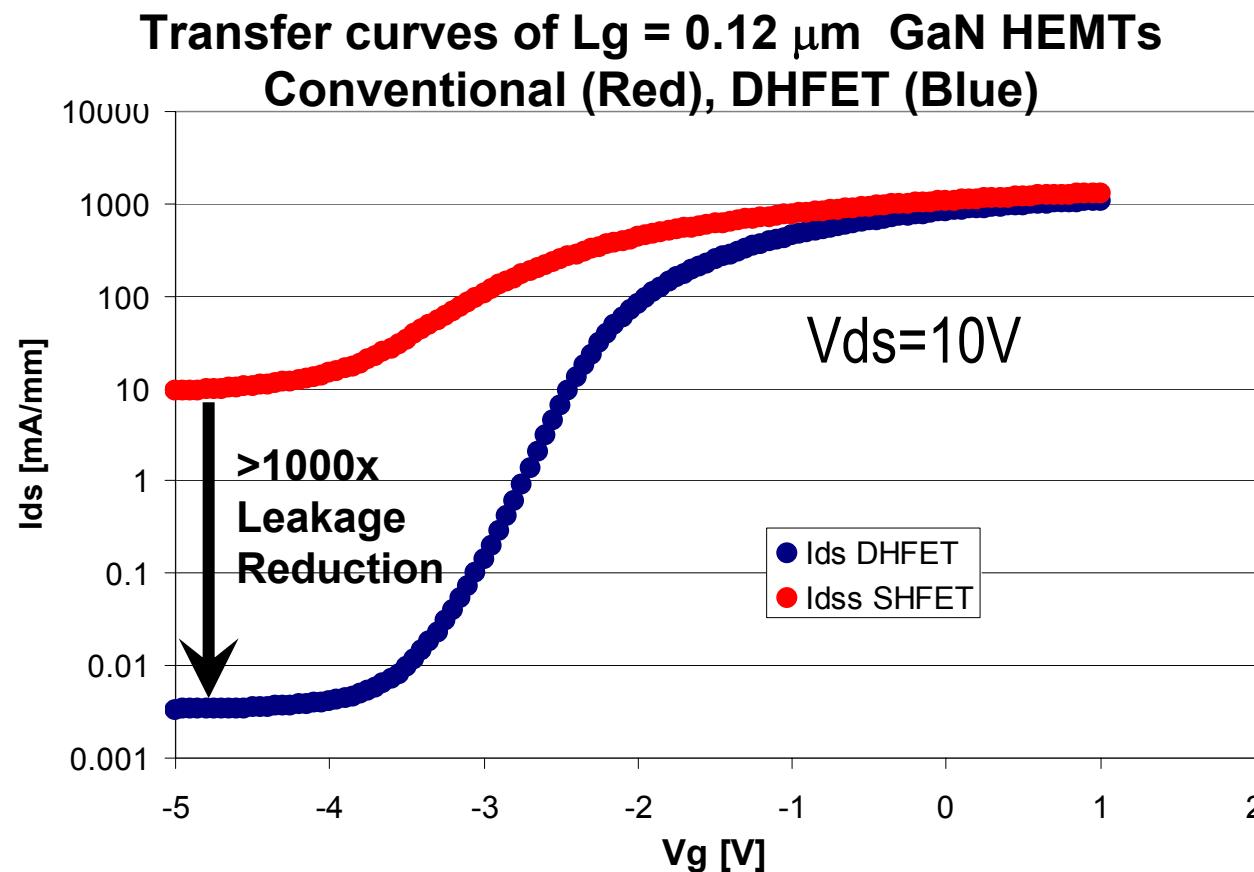
## Doping

- Fe doped buffer layer; Y.-F. Wu et al., El. Dev. Lett., Vol. 25, pp 117-119
- C doped buffer layer; S. Rajan et al., El. Dev. Lett., Vol. 25, pp 247-249

## Polarization Engineering

- GaN DHFET structure; M. Micovic et al., IEDM 2004 Digest, pp 807-810
- InGaN back barrier; T. Palacios et al., El. Dev. Lett., Vol. 27, pp 13-15

# Short Channel Effects - Buffer Isolation

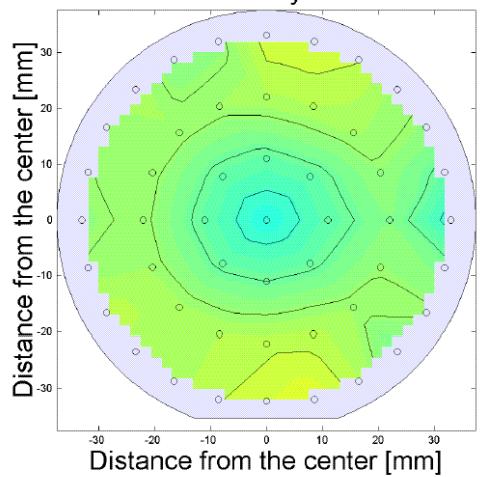


## DHFET Structure:

- Improved Back-Channel Confinement,
- Reduced sub-threshold drain leakage current.

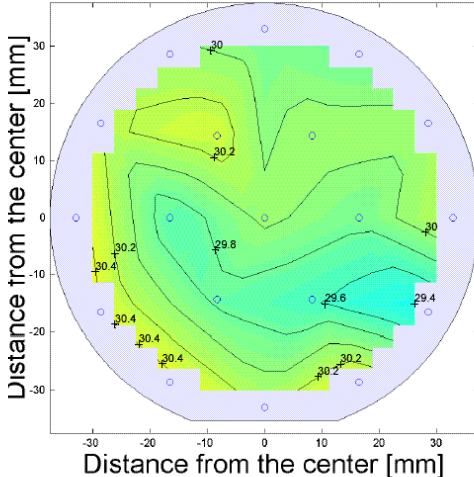
# Uniformity Better than 1% over 3" Wafer

Average value 529.7061 nm  
 Maximum value 538.6 nm  
 Minimum value 516.7 nm  
 Standard deviation 4.8016 nm  
 Wafer Uniformity 0.90646%



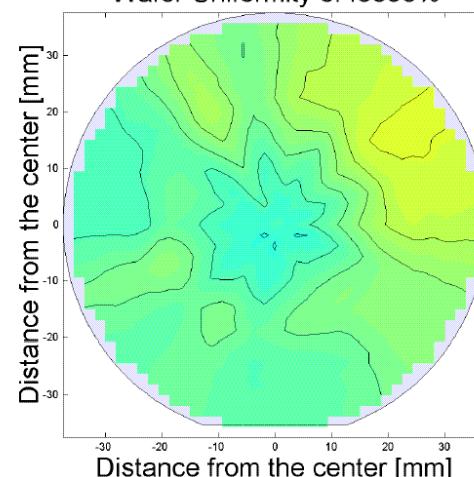
**Epi Thickness 0.90 %**

Average value 29.9852 %  
 Maximum value 30.4529 %  
 Minimum value 29.3999 %  
 Standard deviation 0.20598 %  
 $(\text{Standard Deviation})/\text{Mean} 0.68694\%$



**AlGaN % 0.68 %**

Average value 140.1561 Ohms/square  
 Maximum value 141.5796 Ohms/square  
 Minimum value 138.9568 Ohms/square  
 Standard deviation 0.6503 Ohms/square  
 Wafer Uniformity 0.46398%

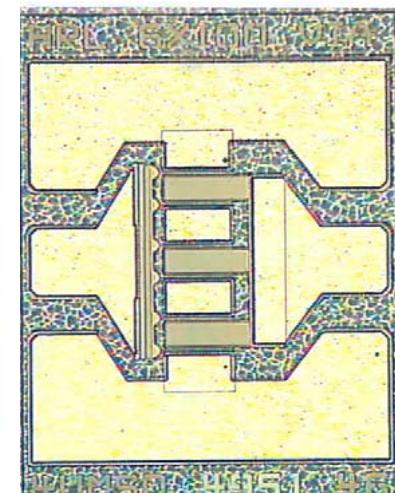
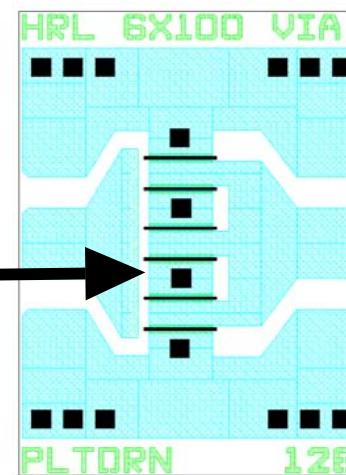
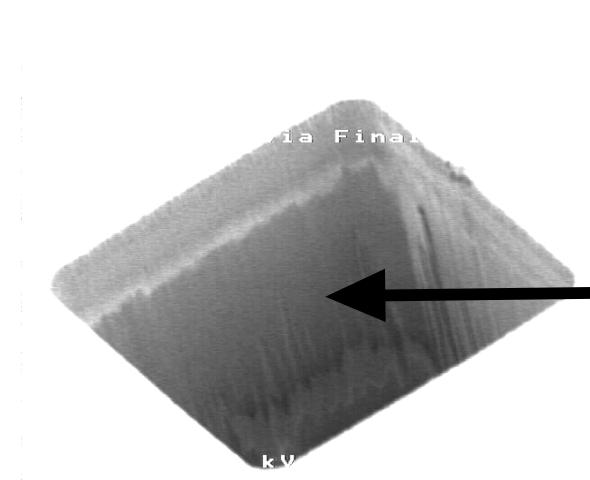


**Sheet resistance 0.46 %**

**Uniformity = Std. Dev. / Mean   No edge exclusion**

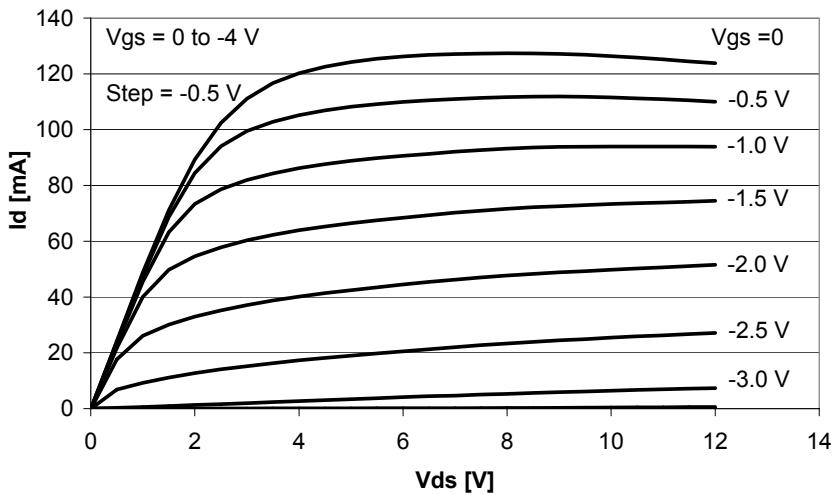
# Individual Source Vias

- 30x30 vertical wall vias in 50  $\mu\text{m}$  substrate
- Enables microstrip MMICs
- Low source inductance < 10 pH
  - Critical for high power W-band power amp performance

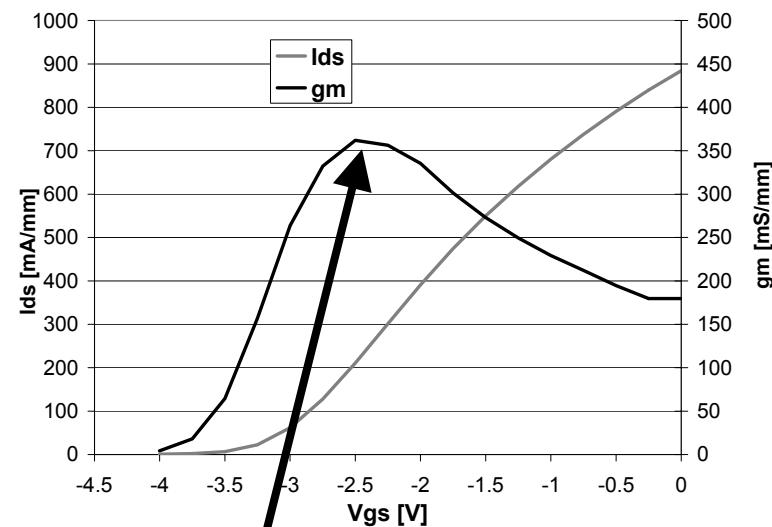


# DC Device Characteristics

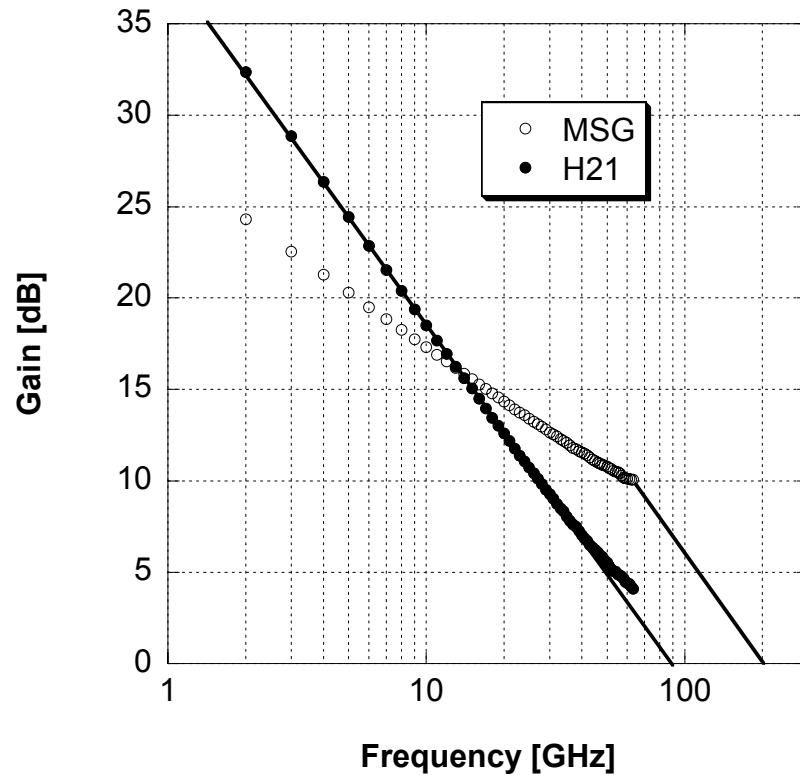
$L_g = 0.1 \mu\text{m}$ ,  $W_g = 4 \times 37.5 \mu\text{m}$  GaN HFET



$$I_{dss} = 900 \text{ mA/mm}$$



# Small Signal RF Performance

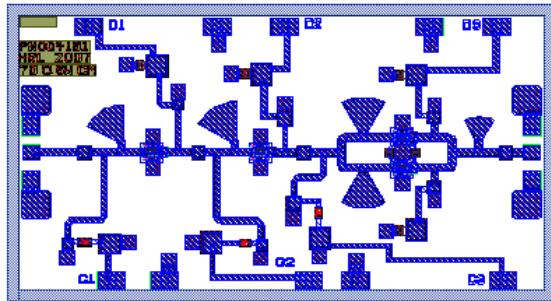


$f_T = 90 \text{ GHz}$

$f_{\max} = 200 \text{ GHz}$

$L_g = 0.1 \mu\text{m}$ ,  $W_g = 4 \times 37.5 \mu\text{m}$  GaN HFET  $V_{ds} = 10 \text{ V}$ ,  $I_{ds} = 45 \text{ mA}$ .

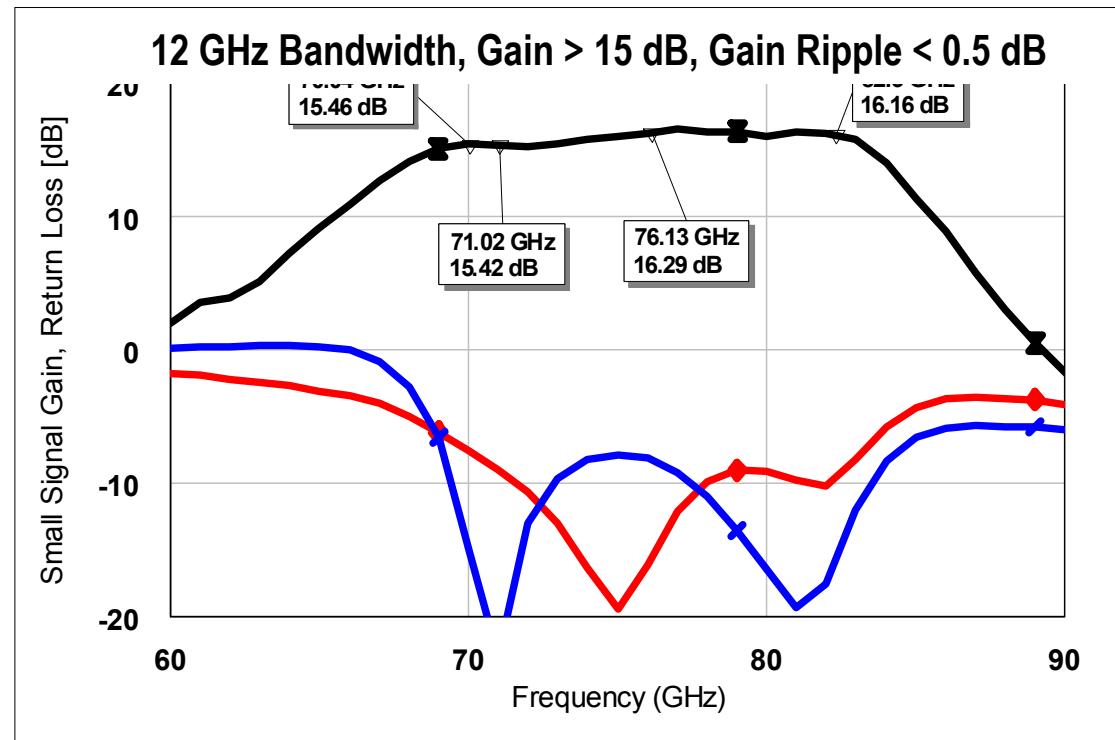
# 500 mW 70 GHz GaN MMIC PA



**70 GHz MMIC Chip Layout**  
Size 3.4 mm x 1.3 mm

**Operating Voltage = 15 V**

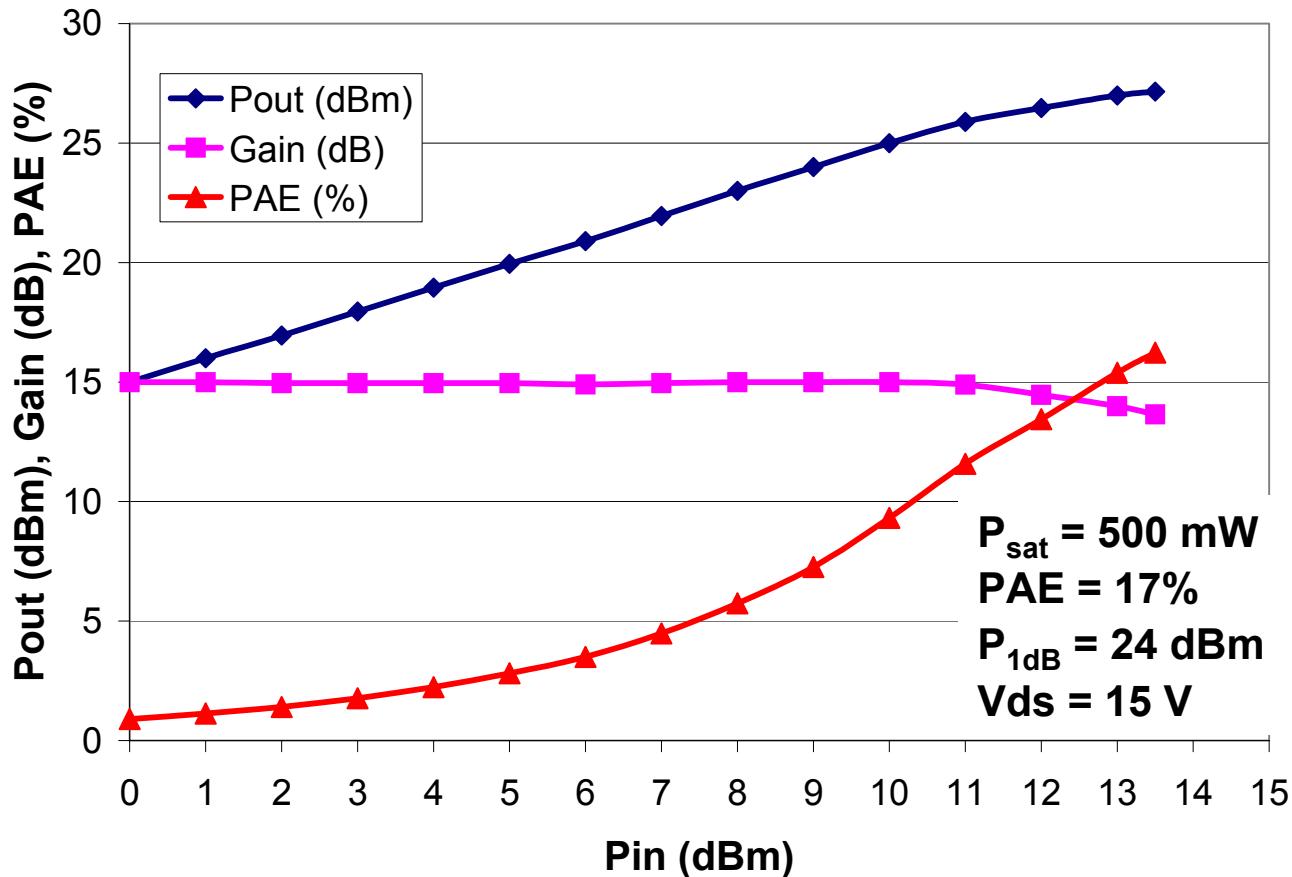
**Measured Gain > 15 dB**



**Measured small signal gain of 70 GHz 500 mW GaN MMIC PA.**

**Performance meets design goal.**

# Output power of 70 GHz MMIC measured at a frequency of 76 GHz



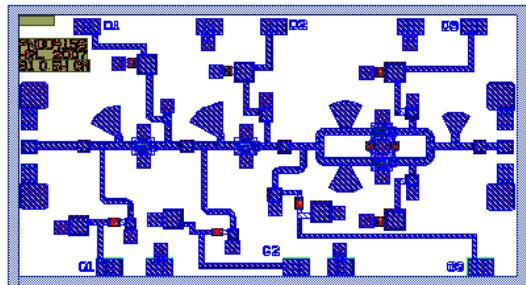
## Comparison of 70 GHZ MMIC Performance with the best commercial pHEMT

Parameter	70 GHz GaN MMIC PA	Commercial GaAs pHEMT
Gain	>14 dB	> 5 dB
P <sub>1dB</sub>	24 dBm	20 dBm
P <sub>sat</sub>	27 dBm	22 dBm
PAE	16.5 %	
Input return loss	< -8 dB	< -4 dB
Output return loss	< - 8 dB	< -2 dB



The most powerful MMIC reported to date at 70 GHz

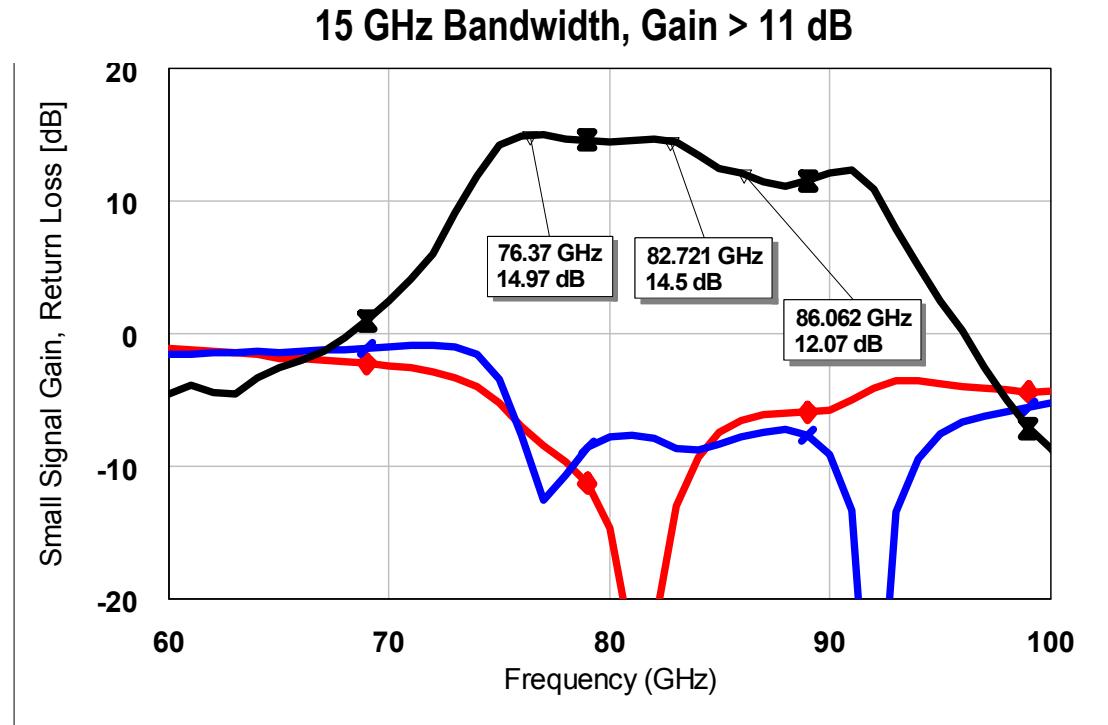
# 500 mW 80 GHz GaN MMIC PA



**80 GHz MMIC Chip Layout**  
Size 3.4 mm x 1.3 mm

**Operating Voltage = 15 V**

**Measured Gain > 11 dB**

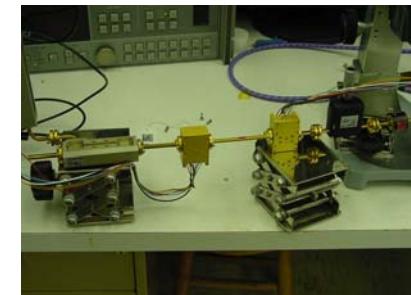
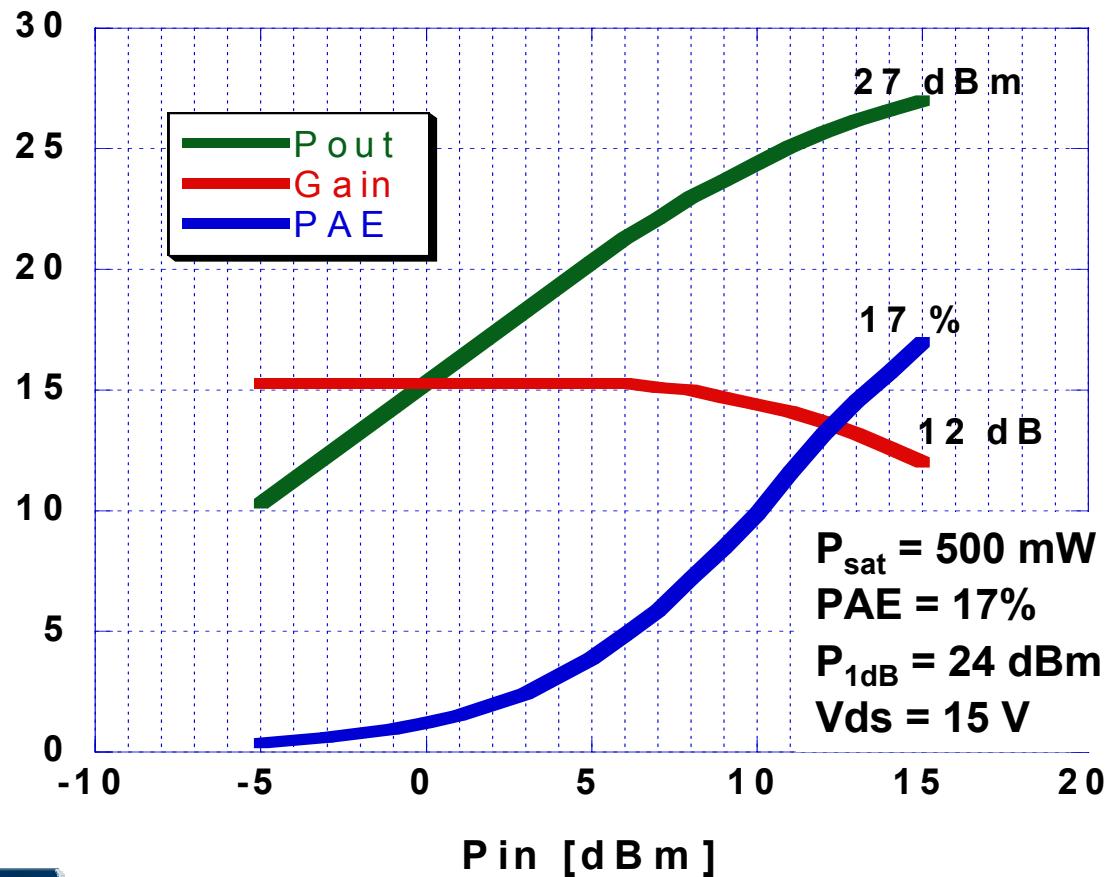


**Measured small signal gain of 80 GHz 500 mW GaN MMIC PA.**

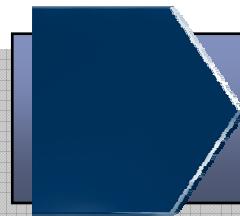
**MMIC Designed for E-band Radio Band**

# Output power of 80 GHz MMIC measured at a frequency of 83 GHz

Pout , Gain, PAE [dBm, dB, %]



Power modules using 2006 GaN SR parts used as a power source.



Highest Output Power and Efficiency reported for a solid state source at this frequency.

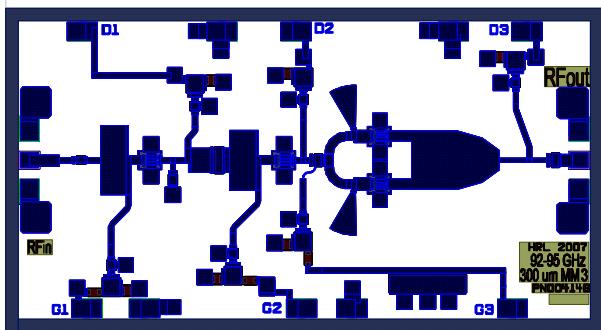
## Comparison of 80 GHZ MMIC Performance with the best commercial pHEMT

Parameter	80 GHz GaN MMIC PA	Commercial GaAs pHEMT
Gain	>11 dB	> 5 dB
P <sub>1dB</sub>	24 dBm	20 dBm
P <sub>sat</sub>	27 dBm	22 dBm
PAE	17 %	
Input return loss	< -7 dB	< -4 dB
Output return loss	< -7dB	< -2 dB



The most powerful MMIC reported to date at 80 GHz

# 500 mW 90 GHz GaN MMIC PA

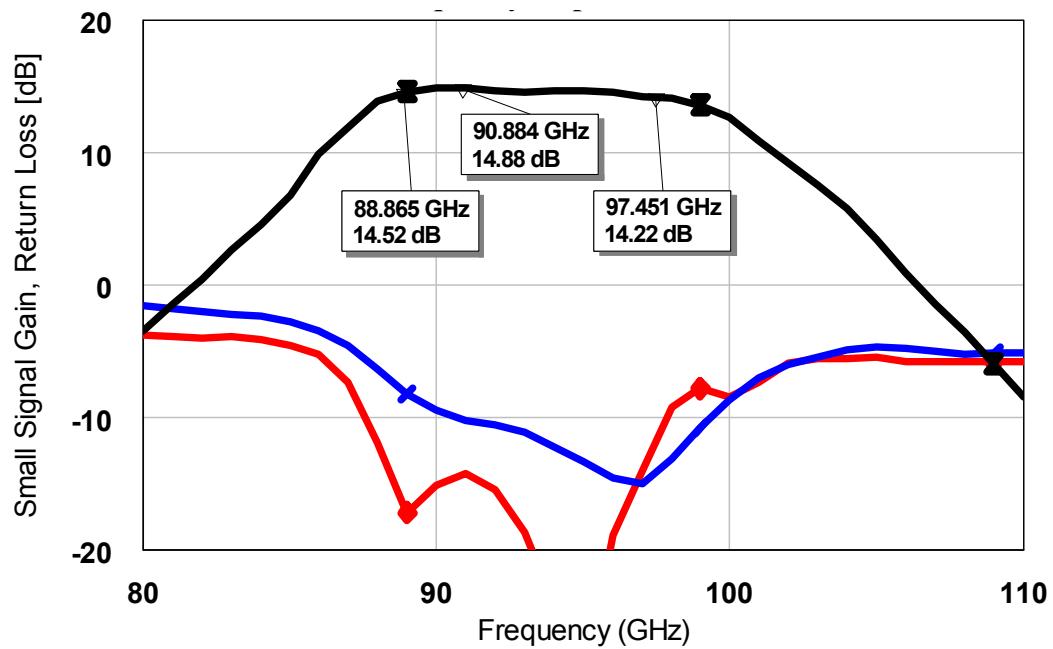


**90 GHz MMIC Chip Layout**  
**Size 2.4 mm x 1.3 mm**

**Operating Voltage = 15 V**

**Measured Gain > 15 dB**

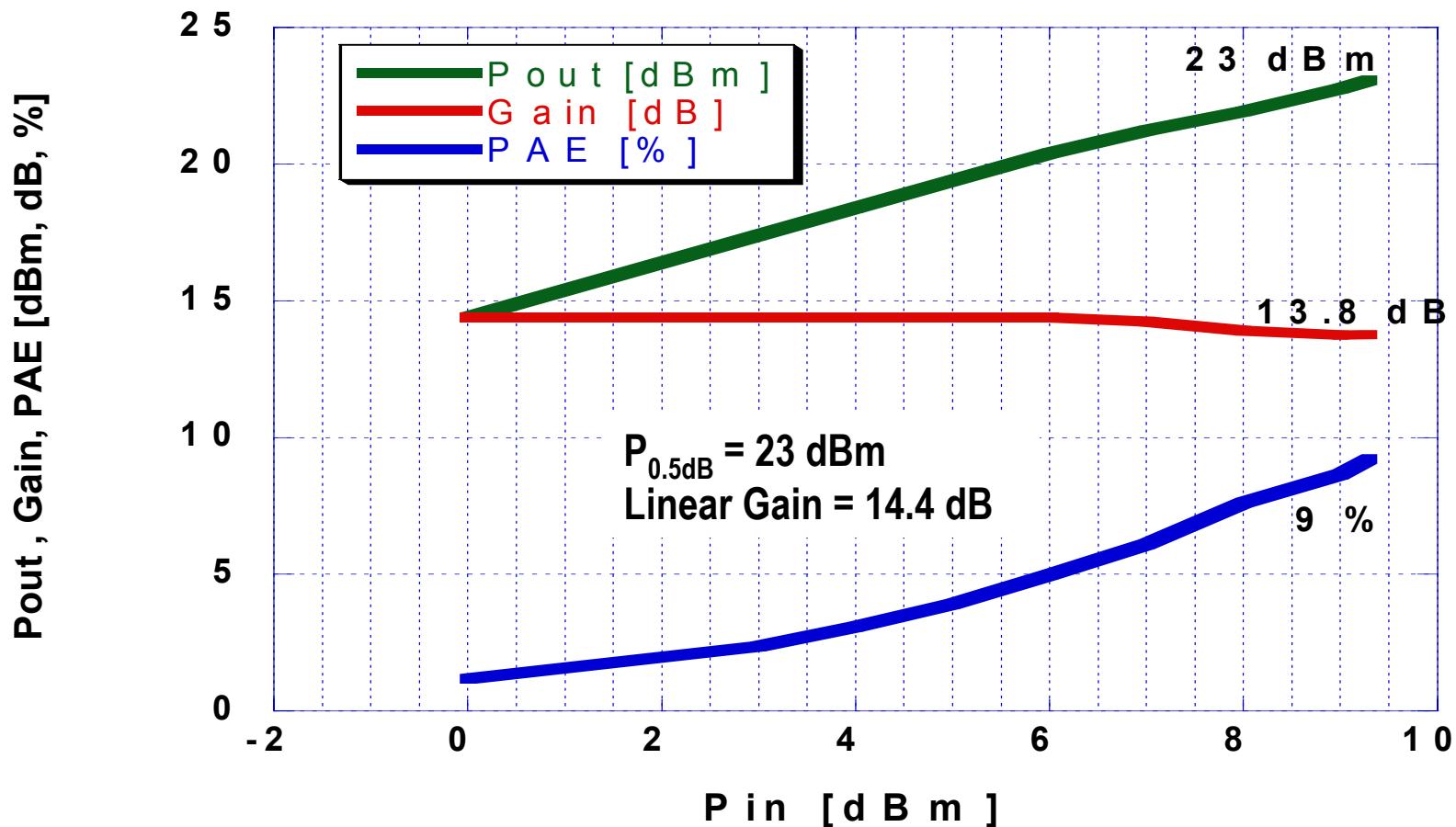
**Flat Response over 92 GHz- 95 GHz frequency band.  
9 GHz Bandwidth, Return Loss < -10 dB**



**Measured small signal gain of 90 GHz 500 mW GaN MMIC PA.**

**Performance Meets Design Goals**

# Output Power of 90 GHz GaN MMIC measured at a frequency of 94.75 GHz



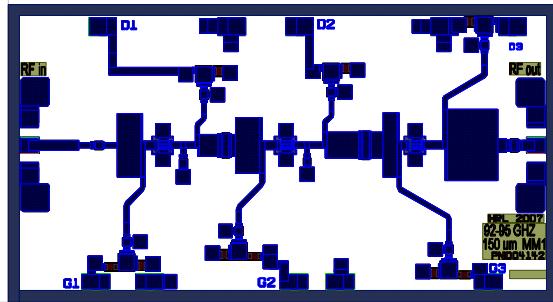
Output power limited by available input drive, circuit less than 0.5 dB compressed.  
HRL is building a power source using GaN MMIC to test the power.



## Comparison of 90 GHZ MMIC Performance with best commercial GaAs pHEMT

Parameter	HRL 90 GHz GaN MMIC PA	GaAs pHEMT
Gain	>14 dB	> 10 dB
Gain Ripple	< 0.5 dB	< 1 dB
P <sub>1dB</sub>	>23 dBm	20 dBm
P <sub>sat</sub>	To be measured	23 dBm
PAE	To be measured	
Input return loss	< -10 dB	< -8 dB
Output return loss	< -10dB	< -8 dB

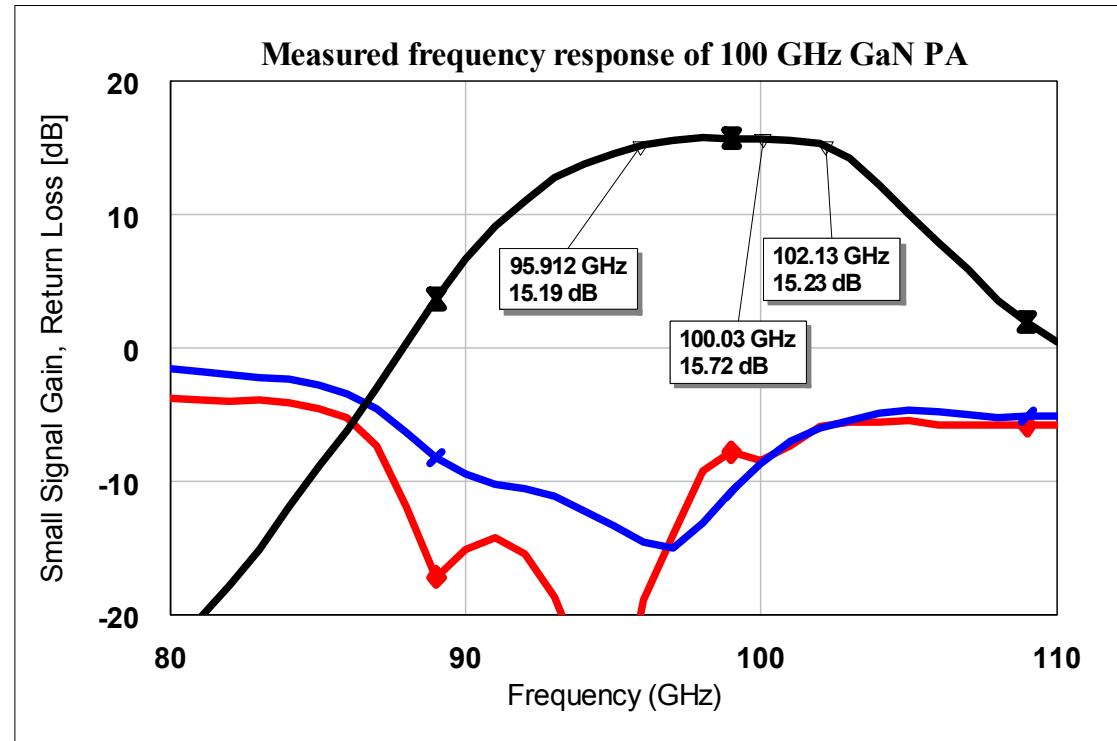
# 250 mW 100 GHz GaN MMIC PA



**100 GHz MMIC Chip Layout**  
**Size 2.4 mm x 1.3 mm**

**Operating Voltage = 15 V**

**Measured Gain > 15 dB**



Measured performance of the first 100 GHz GaN MMIC chip.

**Fastest GaN MMIC Circuit**  
**Near Term Potential for 150 GHz – 220 GHz**

# Summary

- GaN MMIC technology will dominate high frequency > 50 GHz solid state RF power technology.
- Key challenges for MMW GaN:
  - Ohmic Contacts
  - Short gate lengths
  - Device Structure
- GaN MMICs exceeding power of best GaAs and InP MMICs at 95 GHz demonstrated.
- GaN MMICs with 5 x power of the best InP MMICs are on the road map for 2009.

MMW GaN MMIC technology enables new systems, applications and services.

